

# N-Channel Shielded Gate PowerTrench<sup>®</sup> MOSFET 150 V, 2.8 A, 128 m $\Omega$

#### Features

- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)}$  = 128 m $\Omega$  at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 2.8 A
- Max  $r_{DS(on)}$  = 178 m $\Omega$  at  $V_{GS}$  = 6 V,  $I_D$  = 2.4 A
- High Performance Trench Technology for Extremely Low <sup>r</sup>DS(on)
- High Power and Current Handling Capability in a Widely Used Surface Mount Package
- Fast Switching Speed
- 100% UIL Tested
- RoHS Compliant



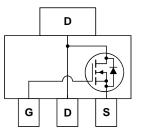
## **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench<sup>®</sup> process that incorporates Shielded Gate technology. This process has been optimized for  $r_{DS(on)}$ , switching performance and ruggedness.

### Applications

- Load Switch
- Primary Switch





# MOSFET Maximum Ratings T<sub>C</sub> = 25 °C unless otherwise noted

Symbol	1	Ratings	Units		
V <sub>DS</sub>	Drain to Source Voltage			150	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
1	Drain Current -Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	2.8	•
D	-Pulsed		12	A	
E <sub>AS</sub>	Single Pulse Avalanche Energy	12	mJ		
Р	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.2	w
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1b)	1.0	vv
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range			-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	12	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	55	0/11

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
86244	FDT86244	SOT-223	13 "	12 mm	2500 units

January 2016

FDT86244 N-Ch
annel
Shielded
N-Channel Shielded Gate PowerTrench <sup>®</sup>
ch <sup>®</sup> MOSFET
Ш —

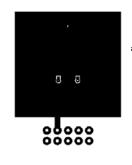
Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Chara	cteristics						
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$	,	150			V
ΔΒV <sub>DSS</sub> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu A$ , reference	d to 25 °C		104		mV/°C
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V	/			1	μA
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	/			±100	nA
On Chara	cteristics						
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu$	A	2.0	3.1	4.0	V
$\Delta V_{GS(th)} \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25 °C			-10		mV/°C
r <sub>DS(on)</sub>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.8 A			106	128	
	Static Drain to Source On Resistance	$V_{GS} = 6 V, I_D = 2.4 A$			127	178	mΩ
		$V_{GS} = 10 \text{ V}, \ I_D = 2.8 \text{ A}, \ T_J = 125 \text{ °C}$			196	237	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.8 A			12		S
Dynamic	Characteristics						
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 75 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ f = 1 MHz			295	395	pF
C <sub>oss</sub>	Output Capacitance				33	45	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				2.4	5	pF
Rg	Gate Resistance				1.0		Ω
Switching	Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time				5.3	11	ns
t <sub>r</sub>	Rise Time	$V_{DD}$ = 75 V, I <sub>D</sub> = 2.8 A, V <sub>GS</sub> = 10 V, R <sub>GEN</sub> = 6 Ω			1.3	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time				9.8	20	ns
t <sub>f</sub>	Fall Time				2.4	10	ns
Q <sub>g(TOT)</sub>	Total Gate Charge	$V_{GS} = 0 V \text{ to } 10 V$			4.9	7	nC
Q <sub>g(TOT)</sub>	Total Gate Charge	$V_{GS} = 0 \text{ V to } 10 \text{ V}$ $V_{GS} = 0 \text{ V to } 5 \text{ V}$ $I_D = 2.8 \text{ A}$			2.8	4	nC
Q <sub>gs</sub>	Total Gate Charge		- 2.0 A		1.4		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge				1.3		nC

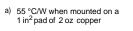
# **Drain-Source Diode Characteristics**

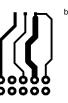
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = 2.8 A$	(Note 2)	0.82	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 2.8 A, di/dt = 100 A/μs		48	77	ns
Q <sub>rr</sub>	Reverse Recovery Charge			44	70	nC

NOTES:

R<sub>0JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.





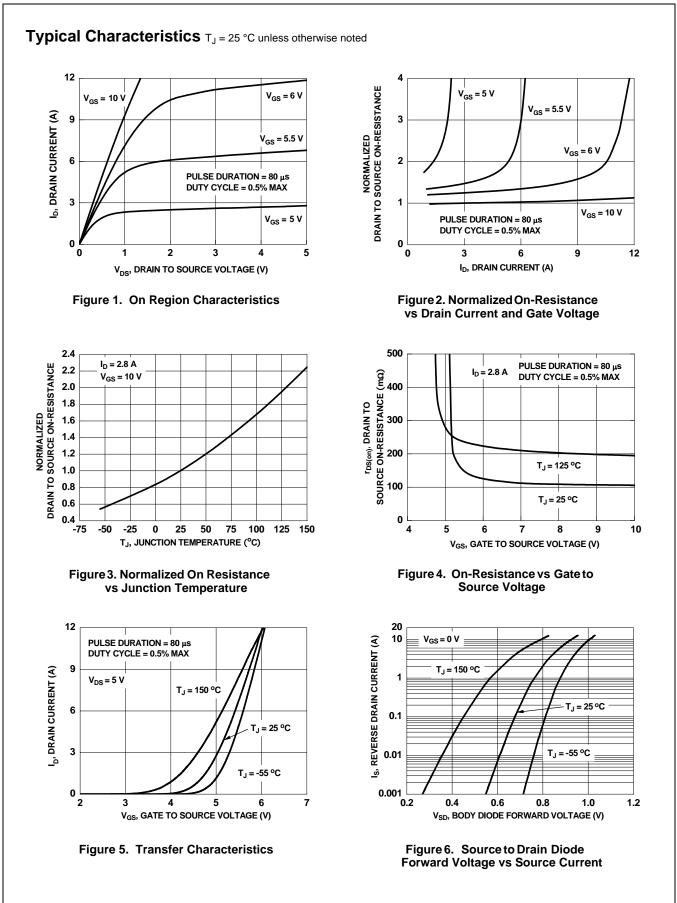


0

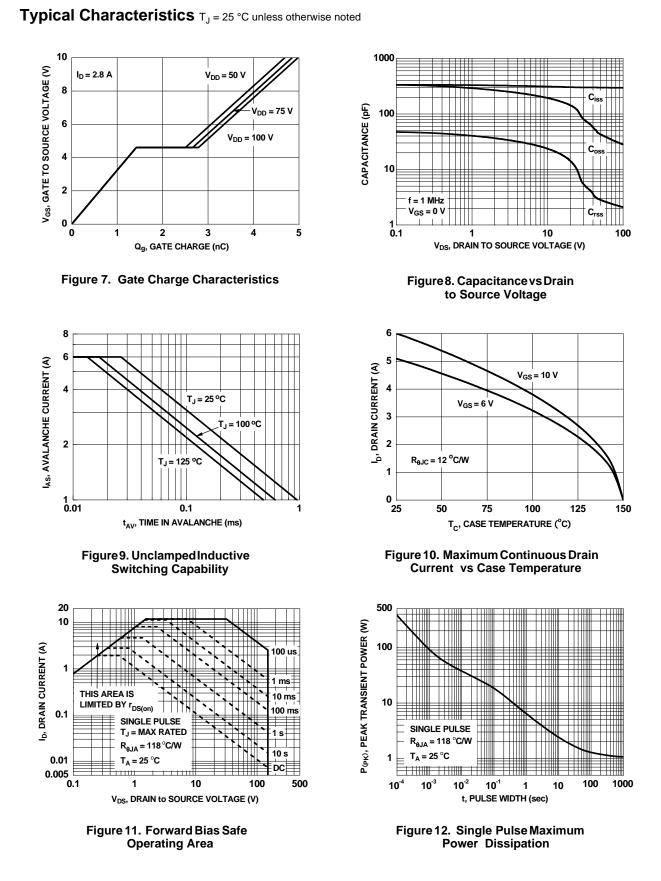
b) 118 °C/W when mounted on a minimum pad of 2 oz copper

3. Starting T<sub>J</sub> = 25 °C; N-ch: L = 1 mH, I<sub>AS</sub> = 5 A, V<sub>DD</sub> = 135 V, V<sub>GS</sub> = 10 V.

2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0%.

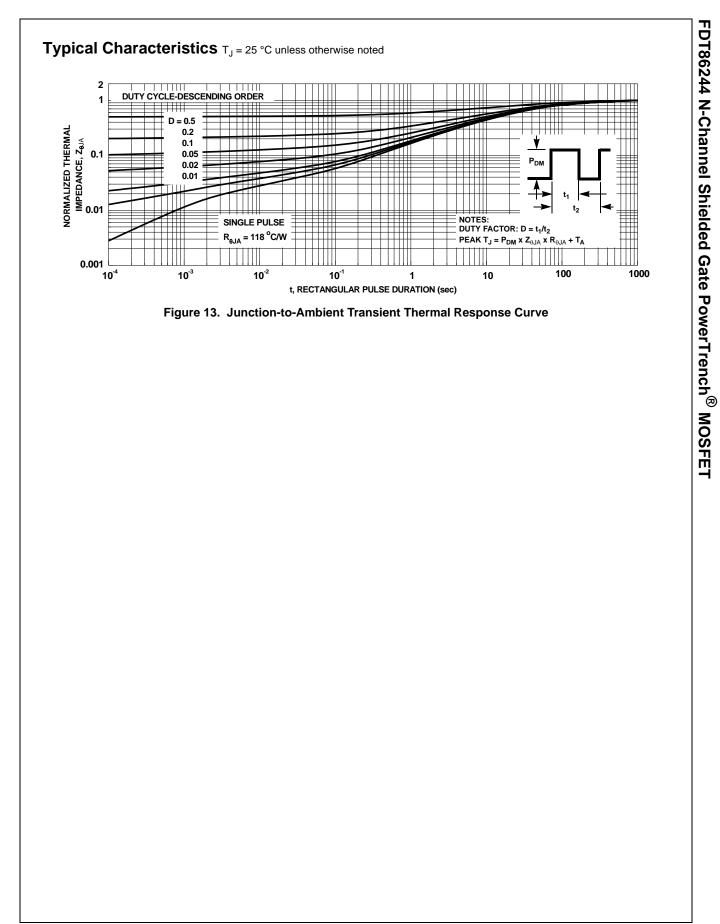


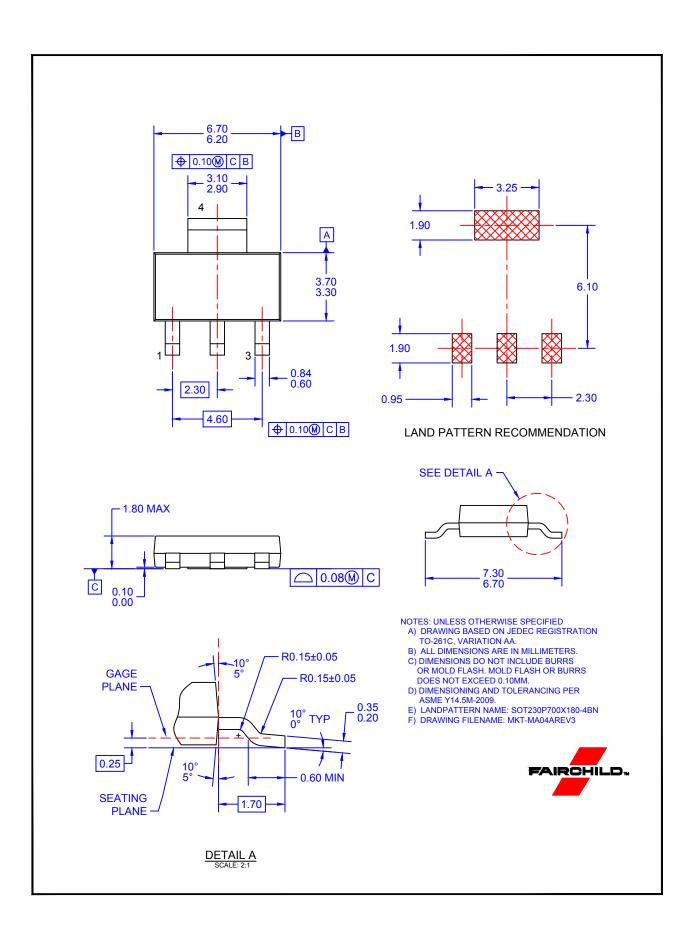
©2011 Fairchild Semiconductor Corporation FDT86244 Rev.1.3



©2011 Fairchild Semiconductor Corporation FDT86244 Rev.1.3

FDT86244 N-Channel Shielded Gate PowerTrench<sup>®</sup> MOSFET







\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT <u>HTTP://WWW.FAIRCHILDSEMI.COM</u>, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### AUTHORIZED USE

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

#### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

Definition of Terms						
Datasheet Identification	Product Status	Definition				
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.				
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.				
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.				
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.				

Rev. 177

# **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Fairchild Semiconductor: <u>FDT86244</u>